



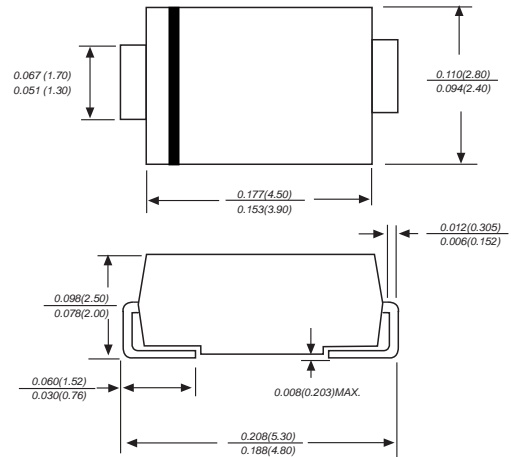
Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Built-in strain relief, ideal for automated placement
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed
250°C/10 seconds at terminals

Mechanical Data

Case : Molded plastic body
 Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
 Polarity : Polarity symbol marking on body
 Mounting Position : Any
 Weight : 0.0023 ounce, 0.07 grams

DO-214AC/SMA



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS34L	SS345L	SS35L	SS36L	SS38L	SS310L	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	40	45	50	60	80	100	V
Maximum RMS voltage	V _{RMS}	28	31.5	35	42	56	70	V
Maximum DC blocking voltage	V _{DC}	40	45	50	60	80	100	V
Maximum average forward rectified current at T _L =100°C	I _(AV)	3.0						A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	80.0						A
Maximum instantaneous forward voltage at 3.0A	V _F	0.48			0.55	0.70		v
Maximum DC reverse current at rated DC blocking voltage T _A = 25°C T _A = 125°C	I _R	0.5 50				0.2 20		mA
Typical thermal resistance	R _{qJA}	80.0						°C/W
Operating junction temperature range	T _J	-55 to +150						°C
Storage temperature range	T _{STG}	-55 to +150						°C



Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

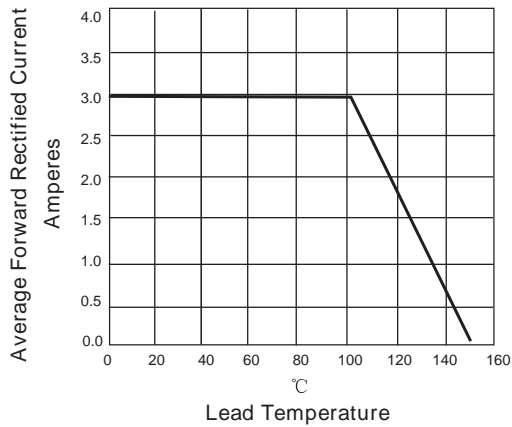


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

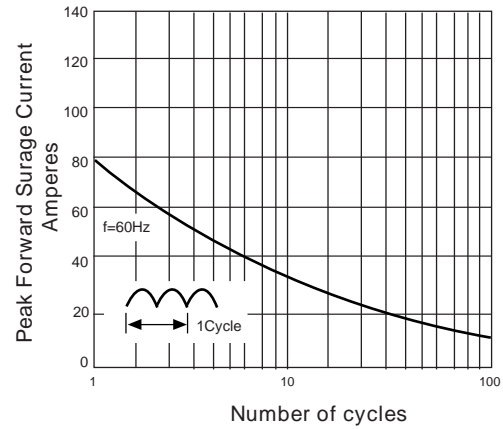


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

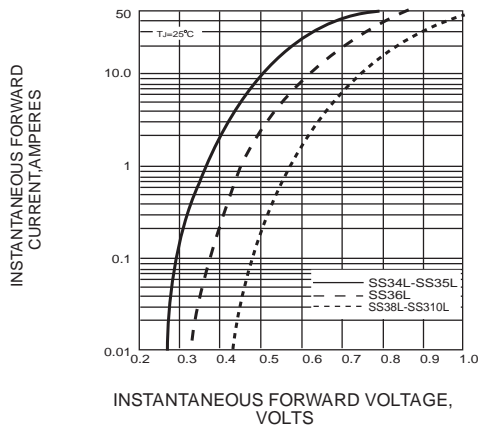
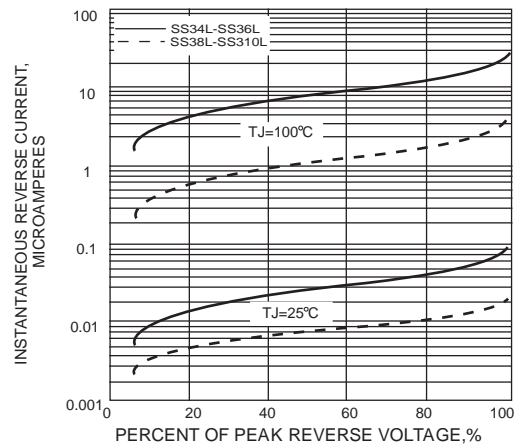
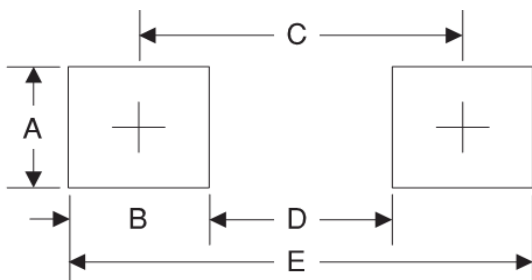


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



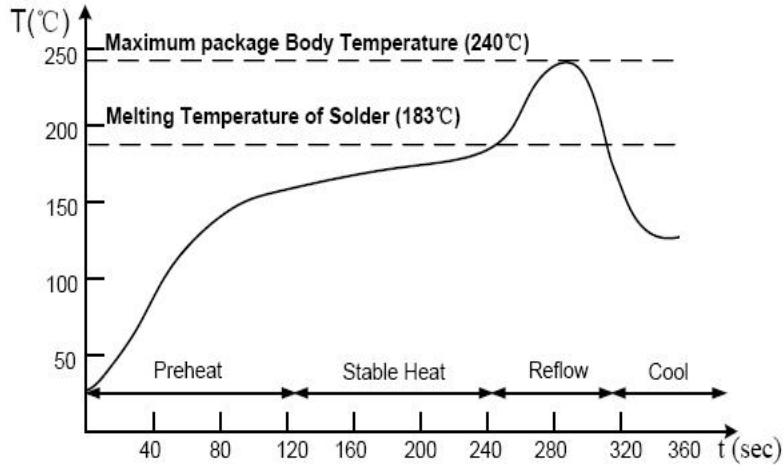
Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.90	0.154
D	2.41	0.095
E	5.45	0.215



Suggested Soldering Temperature Profile

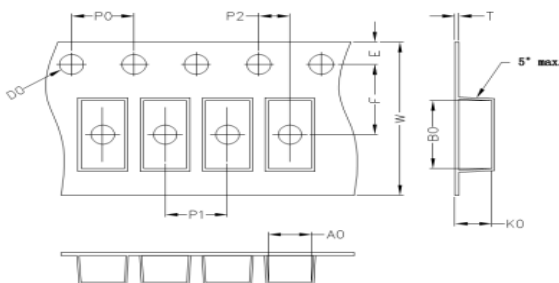


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
2.80	5.30	2.36	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	4.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMA	11'	278	5	285	10	355*310*310	80
	13'	330	7.5	340	15	360*360*360	120